

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5221881

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
GULBAGH SINGH	10/02/2018
CHENG-YEH HUANG	10/08/2018
CHIN-NAN CHANG	10/02/2018
CHIH-MING LEE	10/02/2018
CHI-YEN LIN	10/19/2018
RECEIVING PARTY DATA	
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16179165
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ATTORNEY DOCKET NUMBER:	0941-3818PUS2
NAME OF SUBMITTER:	CHRISTOPHER SMITH
SIGNATURE:	/Christopher Smith/
DATE SIGNED:	11/05/2018
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Gulbagh SINGH, Cheng-Yeh HUANG, Chin-Nan CHANG, Chih-Ming LEE and Chi-Yen LIN

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD FOR FORMING SEMICONDUCTOR DEVICE STRUCTURE WITH METAL SILICIDE LAYER**

Filed: 02-NOV-2018 Serial No. 16179165

Executed on: 02-OCT-2018; 08-OCT-2018; 19-OCT-2018;

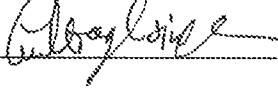
WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2018/10/02 
Date Name: Gulbagh SINGH

2018.10.08 Cheng-Yeh Huang
Date Name: Cheng-Yeh HUANG

2018/10/02 Chin Nan Chang
Date Name: Chin-Nan CHANG

2018/10/02 Chih Ming Lee
Date Name: Chih-Ming LEE

2018/10/19 Chi-Yen Lin
Date Name: Chi-Yen LIN